

1.Base 2.Collector 3.Emitter

NPN Triple Diffused Planar Silicon Transistor

| Absolute Maximum | Ratings $T_{c}=25^{\circ}C$ unless otherwise noted |
|------------------|---|
|------------------|---|

| Symbol | Parameter | Value | Units |
|------------------|----------------------------|------------|-------|
| V _{CBO} | Collector-Base Voltage | 1600 | V |
| V _{CEO} | Collector-Emitter Voltage | 800 | V |
| V _{EBO} | Emitter-Base Voltage | 12 | V |
| I _C | Collector Current (DC) | 3 | А |
| I _{CP} | *Collector Current (Pulse) | 6 | А |
| I _B | Base Current | 2 | А |
| I _{BP} | *Base Current (Pulse) | 4 | А |
| P _C | Power Dissipation(Tc=25) | 80 | W |
| TJ | Junction Temperature | 150 | °C |
| T _{STG} | Storage Temperature | - 65 ~ 150 | °C |

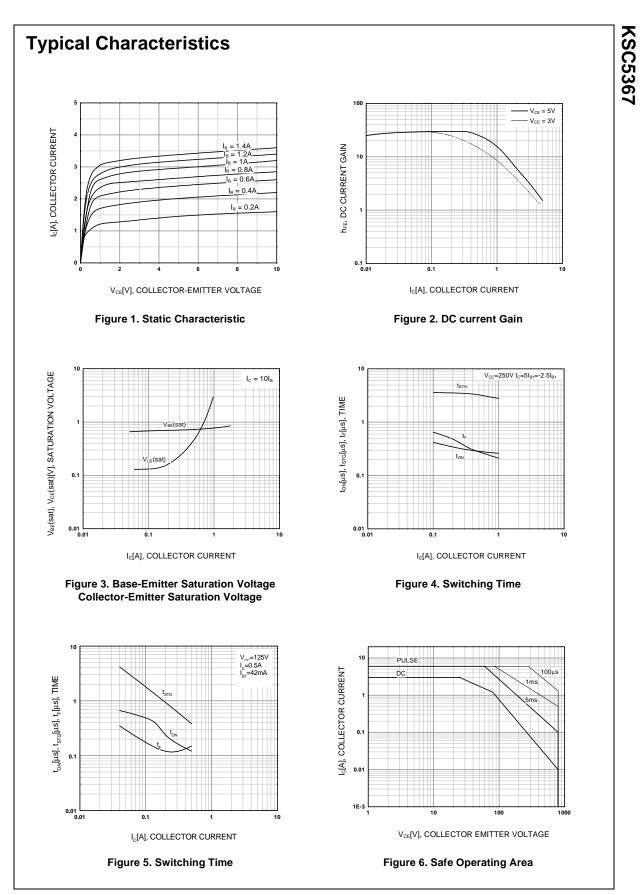
* Pulse Test: Pulse Width=5ms, Duty Cycle≤10%

Thermal Characteristics $T_{C}=25^{\circ}C$ unless otherwise noted

| Symbol | Char | Rating | Unit | |
|------------------|--------------------|---------------------|------|------|
| R _{θjc} | Thermal Resistance | Junction to Case | 1.56 | °C/W |
| $R_{	heta ja}$ | | Junction to Ambient | 62.5 | |

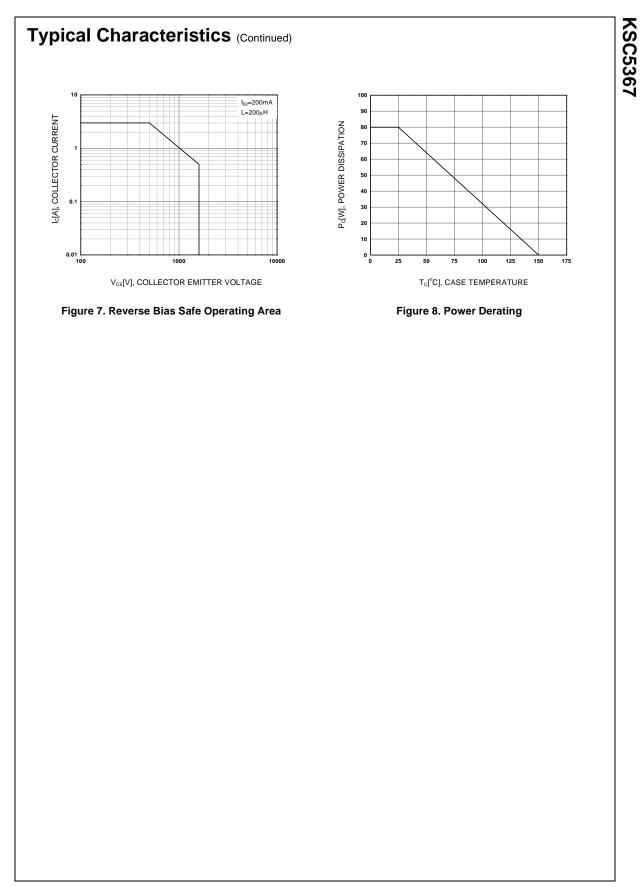
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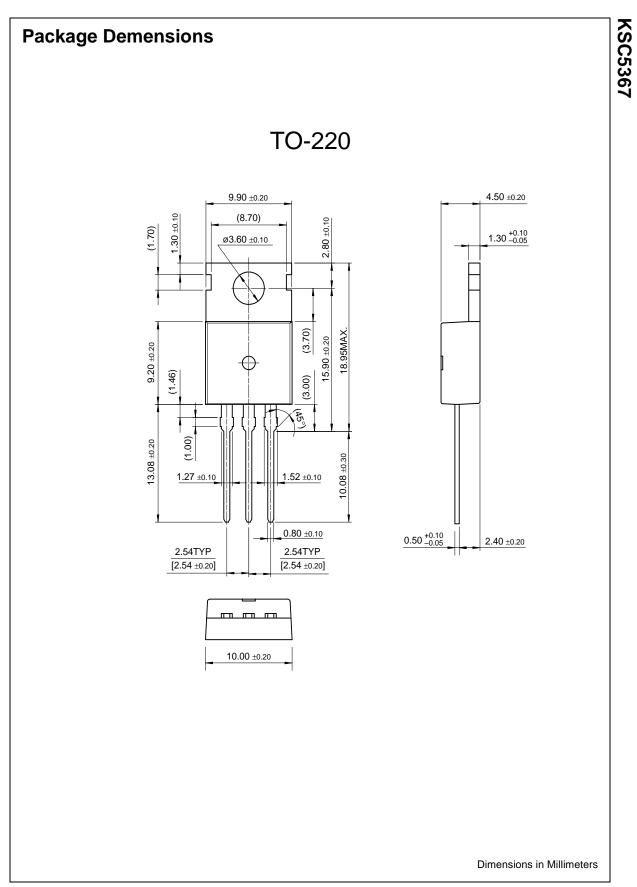
| Symbol | Parameter | Test Condition | Min. | Тур. | Max. | Units |
|--------------------------------------|--------------------------------------|--|-------------|--------|-------------------|-------------|
| BV _{CBO} | Collector-Base Breakdown Voltage | I _C = 1mA, I _E = 0 | 1600 | - | - | V |
| BV _{CEO} | Collector-Emitter Breakdown Voltage | I _C = 5mA, I _B = 0 | 800 | - | - | V |
| BV _{EBO} | Emitter-Base Breakdown Voltage | I _C =0.5mA, I _C = 0 | 12 | - | - | V |
| I _{CBO} | Collector Cut-off Current | V _{CB} = 1,600V, I _E = 0 | - | - | 20 | μA |
| I _{EBO} | Emitter Cut-off Current | V _{EB} = 12V, I _C = 0 | - | - | 20 | μA |
| h _{FE1} h _{FE2} | DC Current Gain | $V_{CE} = 3V, I_{C} = 0.4A$ $V_{CE} = 10V, I_{C} = 5mA$ | 12 8 | - | 35 - | |
| V _{CE} (sat) | Collector-Emitter Saturation Voltage | $I_{C} = 250$ mA, $I_{B} = 25$ mA $I_{C} = 500$ mA, $I_{B} = 50$ mA $I_{C} = 1$ A, $I_{B} = 0.2$ A | - - - | - - | 2.5 4.5 2.5 | V V V |
| V _{BE} (sat) | Base-Emitter Saturation Voltage | I _C = 3A, I _B = 0.6A | - | - | 1.5 | V |
| C _{ob} | Output Capacitance | I _C = 500mA, I _B = 50mA | - | 40 | | pF |
| t _{ON} | Turn ON Time | V _{CC} = 125V, I _C = 0.5A | - | - | 0.5 | μs |
| t _{STG} | Storage Time | I _{B1} = 42mA, I _{B2} = -333mA | | - | 2.2 | μs |
| t _F | Fall Time | $R_L = 250\Omega$ | - | - | 0.5 | μs |
| t _{ON} | Turn ON Time | V _{CC} = 250V, I _C = 1A | - | - | 0.5 | μs |
| t _{STG} | Storage Time | I _{B1} = 0.2A, I _{B2} = -0.4A | - | - | 4.0 | μs |
| t _F | Fall Time | $R_L = 250\Omega$ | - | - | 0.5 | μs |



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|--------------------------|---------------------------|---|
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